

Figure 1

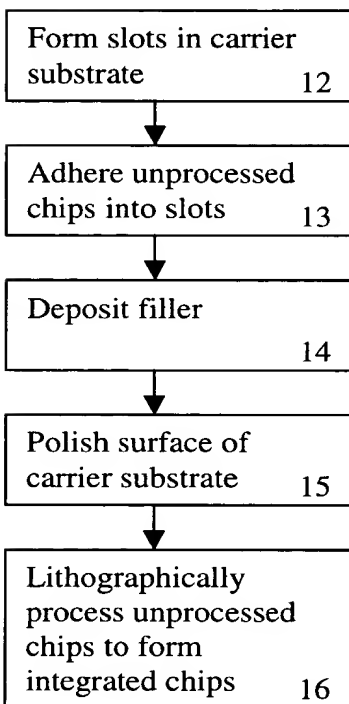


Figure 2

Adhere unprocessed
chips directly onto
carrier substrate
surface 17

Lithographically
process unprocessed
chips to form
integrated chips 18

Figure 3

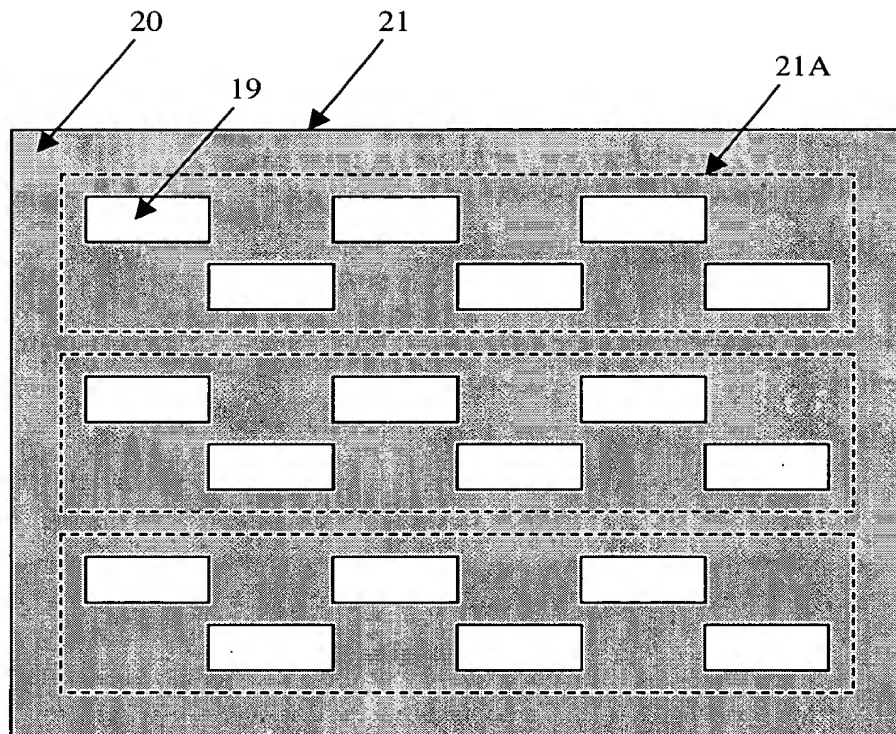


Figure 4

005060 " 46T55960

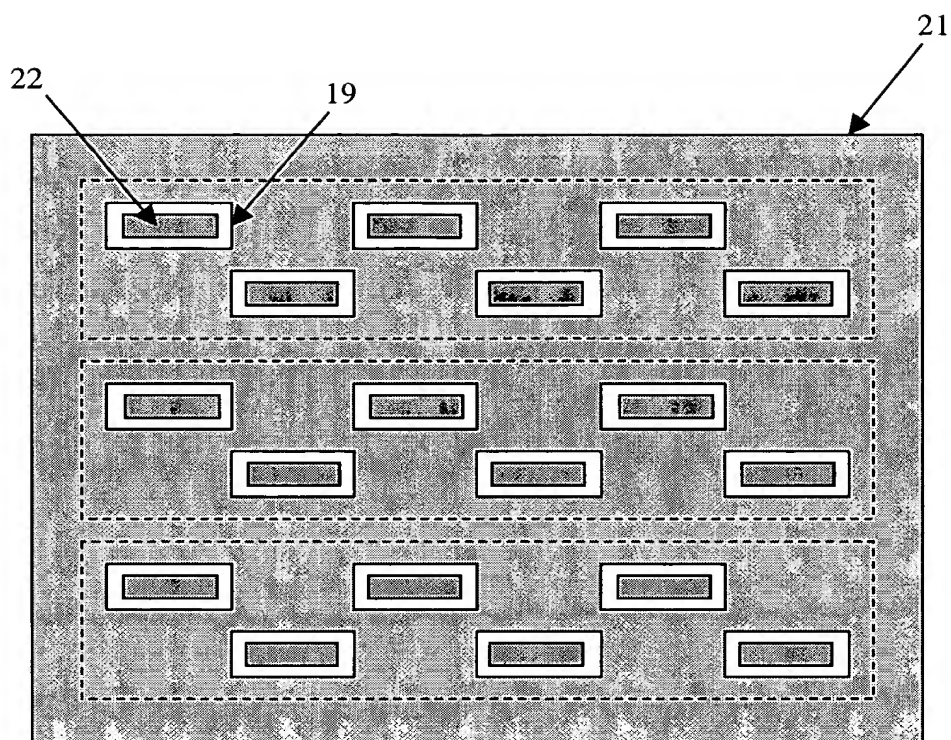


Figure 5A

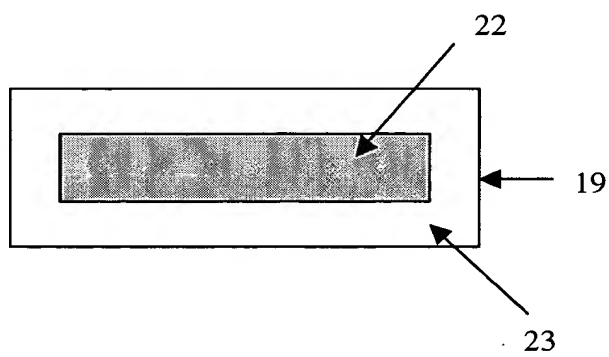


Figure 5B